

**September 9th, 2019**

**Business Segment: ELECTRONICS**

**MacDermid Alpha's Assembly Division to Present Void Reduction Solutions at the FED Conference, Bremen, Germany**

(Waterbury, CT USA) – Sept 9th, 2019 – The Assembly division of MacDermid Alpha Electronics Solutions, a world leader in the production of electronics soldering and bonding materials, will present on the topic of Void Reduction at the FED Conference which runs from 26th-27th September in Bremen, Germany.

Ralph Christ, Customer Technical Support Manager DACH Region for MacDermid Alpha will present "Voiding in Solder Joints: Identifying Causes and Potential Actions Against Void Formation" on Thursday 26th September, 15.30 at the event. "Voids are a major concern for electronic assembly manufacturers as voiding often compromises the reliability of an assembly," comments Ralph. "To combat Voiding a combination of process expertise to understand critical process parameters, design factors and equipment information and innovative products such as solder paste, solder preforms and stencil design is needed."

[ALPHA® Void Reduction Solutions](#) is a proven methodology to address all types of voiding issues in SMT assembly. Alpha experts analyze a customer's process and develop an engineered recommendation addressing material sets, equipment settings and stencil design strategies to produce the desired voiding levels.

MacDermid Alpha Automotive will also present at the conference. Jan-Henryk Serzisko, Strategic Account Director for MacDermid Alpha Automotive will present "[Formable Electronics](#): Process Requirements and Materials for IMSE" on Friday 27th September at 15:00.

To register for the event please visit the [FED Conference website](#). To learn more about ALPHA® Void Reduction Solutions and ALPHA® Products for Formable Electronics visit [www.macdermidalpha.com](http://www.macdermidalpha.com).

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